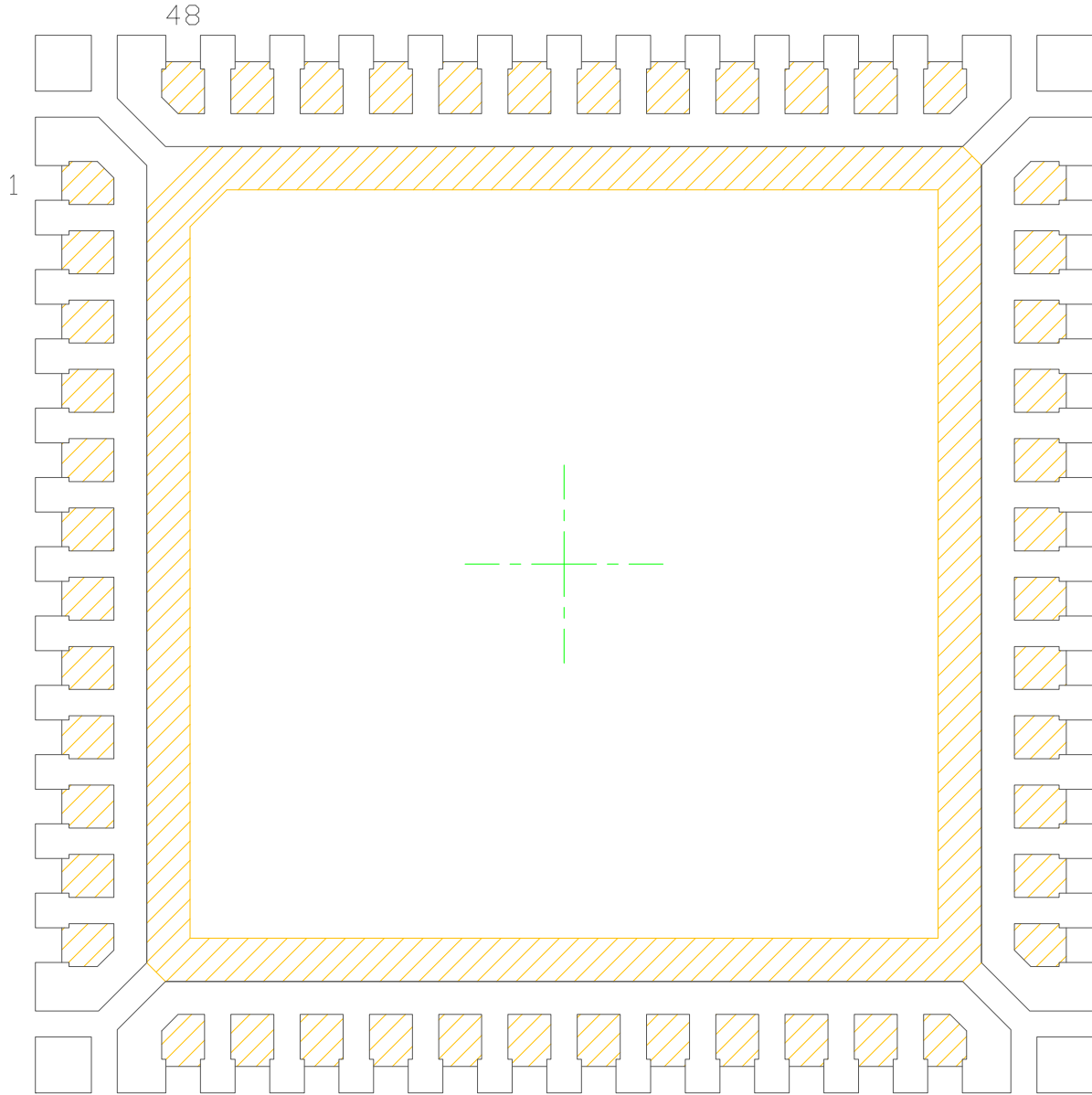



REVISIONS		
REV	DESCRIPTION	DATE
C	INCREASED EXPOSED PAD SIZE, REDUCED GROUND RING WIDTH	07/24/17



 NiPdAu PLATING

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CUSTOMER: xxxxx	DOCUMENT #:	 <a href="http://www.promex-ind.com">www.promex-ind.com</a>		
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 4.82 x 4.82 mm			
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 4.52 x 4.52 mm	TITLE QFN 48L 6x6 mm 0.40 PITCH BOND SHELL		
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: GROUND RING			
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	LEADFRAME P/N: 235-00107 <span style="float: right;">REV 00</span>		
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH			
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	DO NOT SCALE	FILE NAME 48L-QFN-6X6-40P-BD.DWG	SHEET 1 OF 1